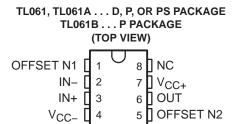
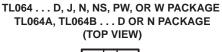
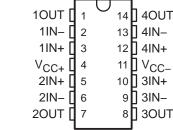
- Very Low Power Consumption
- Typical Supply Current . . . 200 μA (Per Amplifier)
- Wide Common-Mode and Differential Voltage Ranges
- Low Input Bias and Offset Currents
- Common-Mode Input Voltage Range Includes V_{CC+}

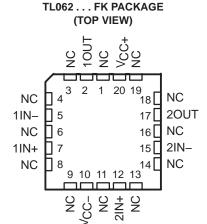
- Output Short-Circuit Protection
- High Input Impedance . . . JFET-Input Stage
- Internal Frequency Compensation
- Latch-Up-Free Operation
- High Slew Rate . . . 3.5 V/μs Typ

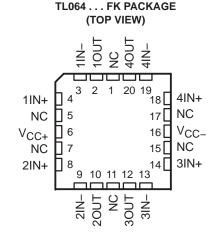






NC - No internal connection





description/ordering information

The JFET-input operational amplifiers of the TL06_ series are designed as low-power versions of the TL08_ series amplifiers. They feature high input impedance, wide bandwidth, high slew rate, and low input offset and input bias currents. The TL06_ series features the same terminal assignments as the TL07_ and TL08_ series. Each of these JFET-input operational amplifiers incorporates well-matched, high-voltage JFET and bipolar transistors in an integrated circuit.

The C-suffix devices are characterized for operation from 0° C to 70° C. The I-suffix devices are characterized for operation from -40° C to 85° C, and the M-suffix devices are characterized for operation over the full military temperature range of -55° C to 125° C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



description/ordering information (continued)

ORDERING INFORMATION

TA	V _{IO} MAX AT 25°C	PACKA	GEŤ	ORDERABLE PART NUMBER	TOP-SIDE MARKING
		DDID (D)	Tube of 50	TL061CP	TL061CP
		PDIP (P)	Tube of 50	TL062CP	TL062CP
		PDIP (N)	Tube of 25	TL064CN	TL064CN
			Tube of 75	TL061CD	TL0040
			Reel of 2500	TL061CDR	TL061C
		COIC (D)	Tube of 75	TL062CD	TL062C
		SOIC (D)	Reel of 2500	TL062CDR	1L062C
	15 mV		Tube of 50	TL064CD	TL064C
	151110		Reel of 2500	TL064CDR	1L064C
		COD (DC)	Dool of 2000	TL061CPSR	T061
		SOP (PS)	Reel of 2000	TL062CPSR	T062
		SOP (NS)	Reel of 2000	TL064CNSR	TL064
			Tube of 150	TL062CPW	Toco
		TSSOP (PW)	Reel of 2000	TL062CPWR	T062
		1330F (FW)	Tube of 90	TL064CPW	T064
			Reel of 2000	TL064CPWR	1004
0°C to 70°C		DDID (D)	T. (50	TL061ACP	TL061ACP
0 0 10 70 0		PDIP (P)	Tube of 50	TL062ACP	TL062ACP
		PDIP (N)	Tube of 25	TL064ACN	TL064ACN
			Tube of 75	TL061ACD	00440
			Reel of 2500	TL061ACDR	061AC
	6 mV	0010 (D)	Tube of 75	TL062ACD	00040
		SOIC (D)	Reel of 2500	TL062ACDR	062AC
			Tube of 50	TL064ACD	TI 00440
			Reel of 2500	TL064ACDR	TL064AC
		COD (DC)	Deal of 0000	TL061ACPSR	T061A
		SOP (PS)	Reel of 2000	TL062ACPSR	T062A
		DDID (D)	Tubo of 50	TL061BCP	TL061BCP
		PDIP (P)	Tube of 50	TL062BCP	TL062BCP
		PDIP (N)	Tube of 25	TL064BCN	TL064BCN
	3 mV		Tube of 75	TL062BCD	00000
		SOIC (D)	Reel of 2500	TL062BCDR	062BC
		SOIC (D)	Tube of 50	TL064BCD	TLOGARC
			Reel of 2500	TL064BCDR	TL064BC

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



description/ordering information (continued)

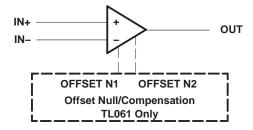
ORDERING INFORMATION (continued)

TA	V _{IO} MAX AT 25°C	PACKAG	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
		DDID (D)	T.h. (50	TL061IP	TL061IP
		PDIP (P)	Tube of 50	TL062IP	TL062IP
		PDIP (N)	Tube of 25	TL064IN	TL064IN
			Tube of 75	TL061ID	TI 0041
4000 4 0500			Reel of 2000	TL061IDR	TL061I
-40°C to 85°C	6 mV	SOIC (D)	Tube of 75	TL062ID	TI 0001
			Reel of 2000	TL062IDR	TL062I
			Tube of 50	TL064ID	TI 0041
			Reel of 2500	TL064IDR	TL064I
		TSSOP (PW)	Reel of 2000	TL062IPWR	TL062I
		CDIP (JG)	Tube of 50	TL062MJG	TL062MJG
	6 mV	LCCC (FK)	Tube of 55	TL062MFK	TL062MFK
–55°C to 125°C		CDIP (J)	Tube of 25	TL064MJ	TL064MJ
	9 mV	CFP (W)	Tube of 150	TL064MW	TL064MW
		LCCC (FK)	Tube of 55	TL064MFK	TL064MFK

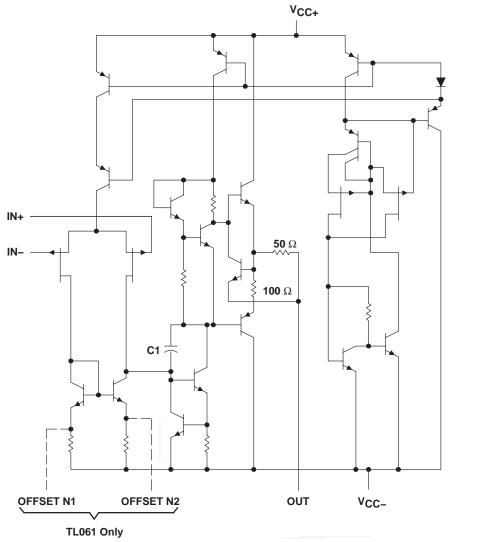
[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



symbol (each amplifier)



schematic (each amplifier)



C1 = 10 pF on TL061, TL062, and TL064 Component values shown are nominal.



TL061, TL061A, TL061B, TL062, TL062A TL062B, TL064, TL064A, TL064B LOW-POWER JFET-INPUT OPERATIONAL AMPLIFIERS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

		TL06_C TL06_AC TL06_BC	TL06_I	TL06_M	UNIT	
Supply voltage, V _{CC+} (see Note 1)		18	18	18	V	
Supply voltage, V _{CC} (see Note 1)		-18	-18	-18	V	
Differential input voltage, V _{ID} (see Note 2)		±30	±30	±30	V	
Input voltage, V _I (see Notes 1 and 3)	±15	±15	±15	V		
Duration of output short circuit (see Note 4)		Unlimited	Unlimited	Unlimited		
	D (8-pin) package	97	97			
	D (14-pin) package	86	86		1	
	N package	80	80		1	
	NS package	76	76		1	
Package thermal impedance, $\theta_{\mbox{\scriptsize JA}}$ (see Notes 5 and 6)	P package	85	85		°C/W	
	PS package	95	95		1	
	PW (8-pin) package	n) package 149 149]	
	PW (14-pin) package	113	113]	
	FK package			5.61		
	J package			15.05	1	
Package thermal impedance, θ _{JC} (see Notes 7 and 8)	JG package			14.5	°C/W	
	W package			14.65]	
Operating virtual junction temperature, T _J		150	150	150	°C	
Case temperature for 60 seconds	FK package			260	°C	
Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds	J, JG, U, or W package			300	°C	
Lead temperature 1,6 mm (1/6 inch) from case for 10 seconds	D, N, NS, P, PS, or PW package	260	260		°C	
Storage temperature range, T _{Stq}		-65 to 150	-65 to 150	-65 to 150	°C	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values except differential voltages are with respect to the midpoint between V_{CC+} and V_{CC-}.

- 2. Differential voltages are at IN+ with respect to IN-.
- 3. The magnitude of the input voltage should never exceed the magnitude of the supply voltage or 15 V, whichever is less.
- 4. The output may be shorted to ground or to either supply. Temperature and/or supply voltages must be limited to ensure that the dissipation rating is not exceeded.
- 5. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
- 6. The package thermal impedance is calculated in accordance with JESD 51-7.
- 7. Maximum power dissipation is a function of $T_J(max)$, θ_{JC} , and T_C . The maximum allowable power dissipation at any allowable case temperature is $P_D = (T_J(max) T_C)/\theta_{JC}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
- 8. The package thermal impedance is calculated in accordance with MIL-STD-883.



TL061, TL061A, TL061B, TL062, TL062A TL062B, TL064, TL064A, TL064B LOW-POWER JFET-INPUT OPERATIONAL AMPLIFIERS

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electrical characteristics, $V_{CC\pm} = \pm 15 \text{ V}$ (unless otherwise noted)

	PARAMETER	TEST CO	onditions†		TL061C TL062C TL064C		Т	L061AC L062AC L064AC		UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
\/	lanut effect veltere	V _O = 0,	T _A = 25°C		3	15		3	6	\/
VIO	Input offset voltage	$R_S = 50 \Omega$	T _A = Full range			20			7.5	mV
$\alpha_{V_{IO}}$	Temperature coefficient of input offset voltage	$V_O = 0$, $R_S = T_A = Full range$			10			10		μV/°C
1	land effect comment	\/- 0	T _A = 25°C		5	200		5	100	pА
lio	Input offset current	VO = 0	T _A = Full range			5			3	nA
lin	Input bias current‡	V _O = 0	T _A = 25°C		30	400		30	200	pA
I _{IB}	input bias current+	ΛΟ = 0	T _A = Full range			10			7	nA
VICR	Common-mode input voltage range	T _A = 25°C		±11	-12 to 15		±11	-12 to 15		٧
.,	, Maximum peak output		T _A = 25°C	±10	±13.5		±10	±13.5		V
V _{OM}	voltage swing	$R_L \ge 10 \text{ k}\Omega$,	T _A = Full range	±10			±10			V
۸ –	Large-signal differential	$V_0 = \pm 10 \text{ V},$	T _A = 25°C	3	6		4	6		V/mV
AVD	voltage amplification	$R_L \ge 10 \text{ k}\Omega$	T _A = Full range	3			4			V/IIIV
B ₁	Unity-gain bandwidth	$R_L = 10 \text{ k}\Omega$,	$T_A = 25^{\circ}C$		1			1		MHz
rį	Input resistance	T _A = 25°C			1012			1012		Ω
CMRR	Common-mode rejection ratio	$V_{IC} = V_{ICR} m$ $R_S = 50 \Omega, T_A$		70	86		80	86		dB
ksvr	Supply-voltage rejection ratio $(\Delta V_{CC\pm}/\Delta V_{IO})$	$V_{CC} = \pm 9 V t$ $V_{O} = 0, R_{S} =$ $T_{A} = 25^{\circ}C$		70	95		80	95		dB
PD	Total power dissipation (each amplifier)	V _O = 0, No load	T _A = 25°C,		6	7.5		6	7.5	mW
Icc	Supply current (each amplifier)	V _O = 0, No load	T _A = 25°C,		200	250		200	250	μА
V _{O1} /V _{O2}	Crosstalk attenuation	$A_{VD} = 100,$	T _A = 25°C		120			120		dB

[†] All characteristics are measured under open-loop conditions with zero common-mode input voltage unless otherwise specified. Full range for TA is 0°C to 70°C for TL06_C, TL06_AC, and TL06_BC and -40°C to 85°C for TL06_I.

[‡] Input bias currents of an FET-input operational amplifier are normal junction reverse currents, which are temperature sensitive, as shown in Figure 15. Pulse techniques are used to maintain the junction temperature as close to the ambient temperature as possible.

electrical characteristics, $V_{CC\pm}$ = ± 15 V (unless otherwise noted)

	PARAMETER	TEST CO	ONDITIONS†	1	L061BC L062BC L064BC	;		TL061I TL062I TL064I		UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
VIO	Input offset voltage	V _O = 0,	T _A = 25°C		2	3		3	6	mV
VIO	input onset voltage	$R_S = 50 \Omega$	T _A = Full range			5			9	111 V
$\alpha_{V_{IO}}$	Temperature coefficient of input offset voltage	$V_O = 0$, $R_S = T_A = Full range$			10			10		μV/°C
1	lanut effect comment	\/- 0	T _A = 25°C		5	100		5	100	pA
lio	Input offset current	VO = 0	T _A = Full range			3			10	nA
	Input bias current‡	\/a 0	T _A = 25°C		30	200		30	200	pА
IB	input bias current+	V _O = 0	T _A = Full range			7			20	nA
VICR	Common-mode input voltage range	T _A = 25°C		±11	–12 to 15		±11	–12 to 15		V
	Maximum peak output	$R_L = 10 \text{ k}\Omega$,	T _A = 25°C	±10	±13.5		±10	±13.5		
Vом	voltage swing	$R_L \ge 10 \text{ k}\Omega$	T _A = Full range	±10			±10			V
	Large-signal differential	$V_0 = \pm 10 \text{ V},$	T _A = 25°C	4	6		4	6		\//\/
AVD	voltage amplification	R _L ≥ 10 kΩ	T _A = Full range	4			4			V/mV
B ₁	Unity-gain bandwidth	$R_L = 10 \text{ k}\Omega$,	$T_A = 25^{\circ}C$		1			1		MHz
rį	Input resistance	T _A = 25°C			1012			1012		Ω
CMRR	Common-mode rejection ratio	V _{IC} = V _{ICR} m R _S = 50 Ω, T _A		80	86		80	86		dB
ksvr	Supply-voltage rejection ratio (\Delta V_CC±/\Delta V_IO)	$V_{CC} = \pm 9 \text{ V t}$ $V_{O} = 0, R_{S} =$ $T_{A} = 25^{\circ}C$		80	95		80	95		dB
PD	Total power dissipation (each amplifier)	V _O = 0, No load	$T_A = 25^{\circ}C$,		6	7.5		6	7.5	mW
lcc	Supply current (each amplifier)	V _O = 0, No load	$T_A = 25^{\circ}C$,		200	250		200	250	μА
VO1/VO2	Crosstalk attenuation	$A_{VD} = 100,$	T _A = 25°C		120			120		dB

[†] All characteristics are measured under open-loop conditions with zero common-mode input voltage, unless otherwise specified. Full range for T_A is 0°C to 70°C for TL06_C, TL06_AC, and TL06_BC and -40°C to 85°C for TL06_I.
‡ Input bias currents of an FET-input operational amplifier are normal junction reverse currents, which are temperature sensitive, as shown in Figure 15. Pulse techniques are used to maintain the junction temperature as close to the ambient temperature as possible.

TL061, TL061A, TL061B, TL062, TL062A TL062B, TL064, TL064A, TL064B LOW-POWER JFET-INPUT OPERATIONAL AMPLIFIERS

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electrical characteristics, $V_{CC\pm} = \pm 15 \text{ V}$ (unless otherwise noted)

	PARAMETER	TEST (CONDITIONS†		TL061M TL062M			TL064M		UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
	land Markerland	V _O = 0,	T _A = 25°C		3	6		3	9	>/
VIO	Input offset voltage	$R_S = 50 \Omega$	$T_A = -55^{\circ}C \text{ to } 125^{\circ}C$			9			15	mV
$\alpha_{V_{IO}}$	Temperature coefficient of input offset voltage	$V_O = 0$, $R_S = 9$ $T_A = -55^{\circ}C$ to			10			10		μV/°C
			T _A = 25°C		5	100		5	100	рА
liO	Input offset current	V _O = 0	T _A = −55°C			20*			20*	nA
			T _A = 125°C			20			20	IIA
			T _A = 25°C		30	200		30	200	рА
I _{IB}	Input bias current‡	V _O = 0	$T_A = -55^{\circ}C$			50*			50*	nA
			T _A = 125°C			50			50	IIA
VICR	Common-mode input voltage range	T _A = 25°C		±11.5	-12 to 15		±11.5	–12 to 15		V
.,	Maximum peak output	$R_L = 10 \text{ k}\Omega$,	T _A = 25°C	±10	±13.5		±10	±13.5		.,
VOM	voltage swing	$R_L \ge 10 \text{ k}\Omega$,	$T_A = -55^{\circ}C$ to $125^{\circ}C$	±10			±10			V
۸۰۰	Large-signal differential	V _O = ±10 V,	T _A = 25°C	4	6		4	6		V/mV
AVD	voltage amplification	R _L ≥ 10 kΩ	$T_A = -55^{\circ}C \text{ to } 125^{\circ}C$	4			4			V/IIIV
B ₁	Unity-gain bandwidth	$R_L = 10 \text{ k}\Omega$,	T _A = 25°C							MHz
rį	Input resistance	T _A = 25°C			1012			1012		Ω
CMRR	Common-mode rejection ratio	V _{IC} = V _{ICR} mi R _S = 50 Ω, T _A		80	86		80	86		dB
k _{SVR}	Supply-voltage rejection ratio (ΔV _{CC±} /ΔV _{IO})	$V_{CC} = \pm 9 \text{ V to}$ $R_S = 50 \Omega, T_A$	±15 V, V _O = 0, = 25°C	80	95		80	95		dB
PD	Total power dissipation (each amplifier)	V _O = 0, No load	$T_A = 25^{\circ}C$,		6	7.5		6	7.5	mW
Icc	Supply current (each amplifier)	V _O = 0, No load	$T_A = 25^{\circ}C$,		200	250		200	250	μΑ
V _{O1} /V _{O2}	Crosstalk attenuation	$A_{VD} = 100,$	$T_A = 25^{\circ}C$		120			120		dB

^{*} This parameter is not production tested.

operating characteristics, $V_{CC\pm}$ = ± 15 V, T_A = $25^{\circ}C$

	PARAMETER	TEST C	TEST CONDITIONS			MAX	UNIT
SR	Slew rate at unity gain (see Note 5)	$V_I = 10 \text{ V},$ $R_L = 10 \text{ k}\Omega,$	C _L = 100 pF, See Figure 1	1.5	3.5		V/µs
t _r	Rise time	V _I = 20 mV,	$R_L = 10 \text{ k}\Omega$		0.2		
	Overshoot factor	$C_L = 100 \text{ pF},$	See Figure 1		10%		μs
٧n	Equivalent input noise voltage	$R_S = 20 \Omega$,	f = 1 kHz		42		nV/√ Hz

NOTE 5: Slew rate at $-55^{\circ}C$ to $125^{\circ}C$ is $0.7 \text{ V/}\mu\text{s min.}$



[†] All characteristics are measured under open-loop conditions, with zero common-mode voltage, unless otherwise specified.

[‡] Input bias currents of an FET-input operational amplifier are normal junction reverse currents, which are temperature sensitive, as shown in Figure 15. Pulse techniques are used to maintain the junction temperature as close to the ambient temperature as possible.

PARAMETER MEASUREMENT INFORMATION

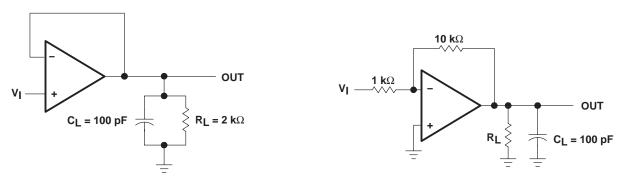


Figure 1. Unity-Gain Amplifier

Figure 2. Gain-of-10 Inverting Amplifier

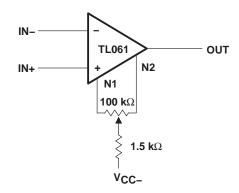


Figure 3. Input Offset-Voltage Null Circuit



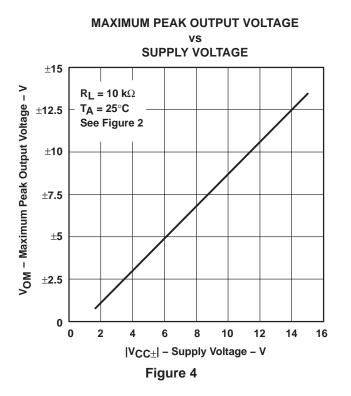
TYPICAL CHARACTERISTICS

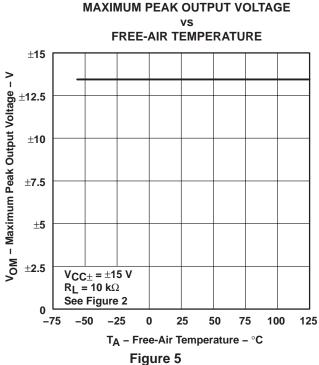
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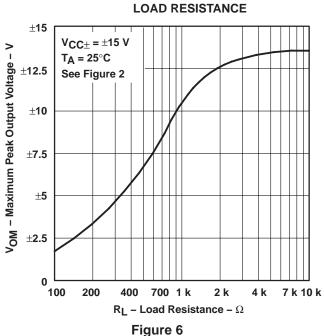


TYPICAL CHARACTERISTICS[†]

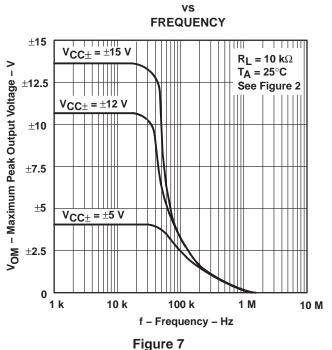




MAXIMUM PEAK OUTPUT VOLTAGE vs



MAXIMUM PEAK OUTPUT VOLTAGE



[†] Data at high and low temperatures are applicable only within the specified operating free-air temperature ranges of the various devices.



TYPICAL CHARACTERISTICS[†]

DIFFERENTIAL VOLTAGE AMPLIFICATION

FREE-AIR TEMPERATURE

10

VCC $\pm = \pm 15$ V

RL = 10 k Ω 7

RL = 10 k Ω 1 -75 -50 -25 0 25 50 75 100 125

Figure 8

T_A - Free-Air Temperature - °C

LARGE-SIGNAL DIFFERENTIAL VOLTAGE AMPLIFICATION AND PHASE SHIFT

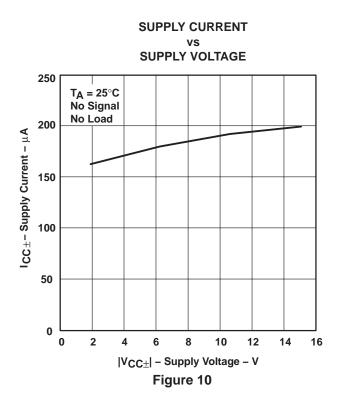
FREQUENCY 100 $V_{CC\pm} = \pm 15 \text{ V}$ $R_{ext} = 0$ $R_L = 10 \text{ k}\Omega$ **0**° 10 A_{VD}- Large-Signal Differential Voltage Amplification – V/mV $T_A = 25^{\circ}C$ **Phase Shift** Phase Shift 45° 1 (right scale) 90° 0.1 AVD (left scale) 0.01 135° 180° 0.001 100 10 k 10 1 k 100 k 1 M 10 M f - Frequency - Hz

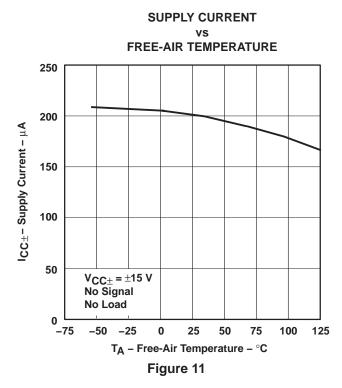
Figure 9

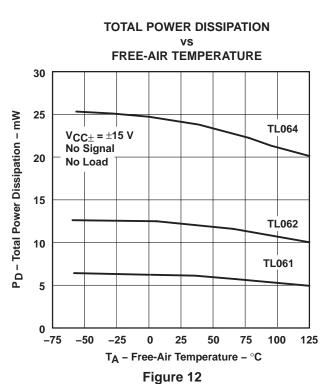
† Data at high and low temperatures are applicable only within the specified operating free-air temperature ranges of the various devices.

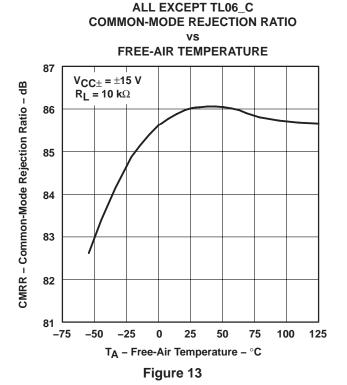


TYPICAL CHARACTERISTICS[†]









[†] Data at high and low temperatures are applicable only within the specified operating free-air temperature ranges of the various devices.



TYPICAL CHARACTERISTICS

NORMALIZED UNITY-GAIN BANDWIDTH, SLEW RATE, AND PHASE SHIFT

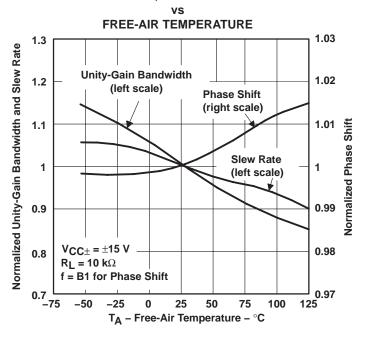
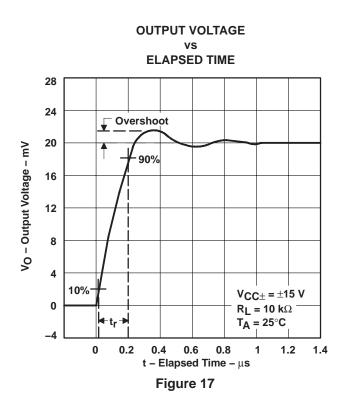


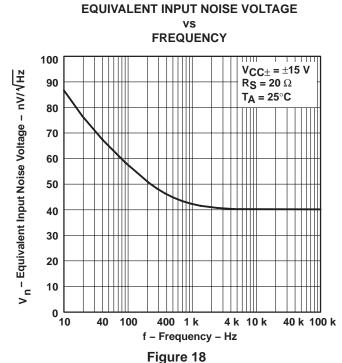
Figure 14

VOLTAGE-FOLLOWER LARGE-SIGNAL PULSE RESPONSE **INPUT BIAS CURRENT** vs TIME FREE-AIR TEMPERATURE 6 100 Input $V_{CC\pm} = \pm 15 V$ 40 4 Input and Output Voltages - V IB - Input Bias Current - nA 10 2 0 Output 0.4 -2 $V_{CC\pm} = \pm 15 \text{ V}$ 0.1 $R_L = 10 \text{ k}\Omega$ -4 C_L = 100 pF 0.04 T_A = 25°C 0.01 -6 50 75 100 -50 -25 125 0 10 T_A - Free-Air Temperature - °C t - Time - μs Figure 15 Figure 16



TYPICAL CHARACTERISTICS





APPLICATION INFORMATION

Table of Application Diagrams

APPLICATION DIAGRAM	PART NUMBER	FIGURE
Instrumentation amplifier	TL064	19
0.5-Hz square-wave oscillator	TL061	20
High-Q notch filter	TL061	21
Audio-distribution amplifier	TL064	22
Low-level light detector preamplifier	TL061	23
AC amplifier	TL061	24
Microphone preamplifier with tone control	TL061	25
Instrumentation amplifier	TL062	26
IC preamplifier	TL062	27

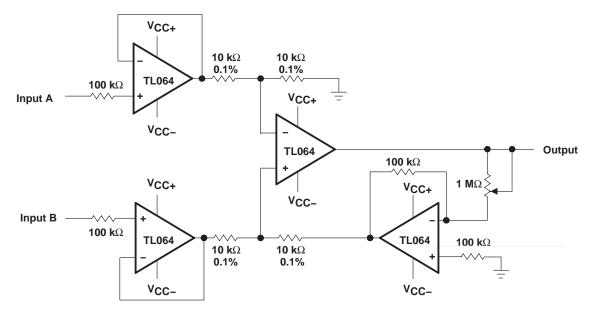


Figure 19. Instrumentation Amplifier

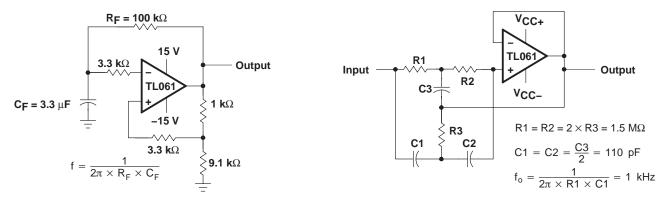


Figure 20. 0.5-Hz Square-Wave Oscillator

Figure 21. High-Q Notch Filter



APPLICATION INFORMATION

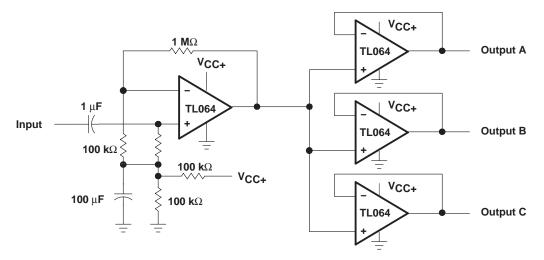


Figure 22. Audio-Distribution Amplifier

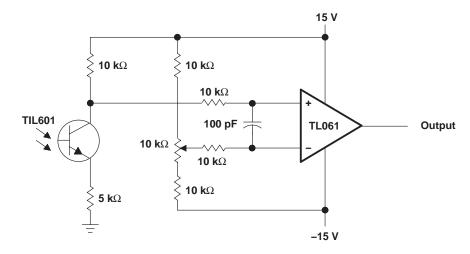


Figure 23. Low-Level Light Detector Preamplifier

APPLICATION INFORMATION

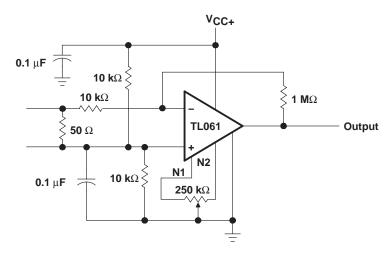


Figure 24. AC Amplifier

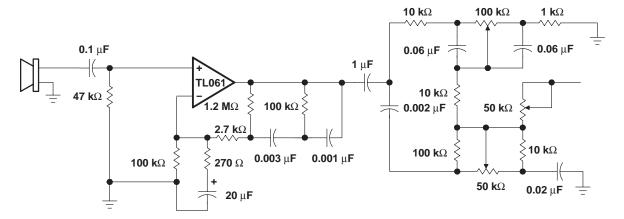


Figure 25. Microphone Preamplifier With Tone Control

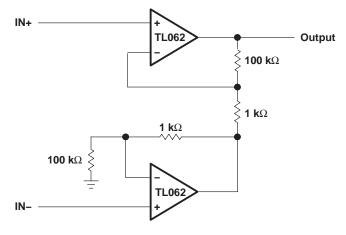
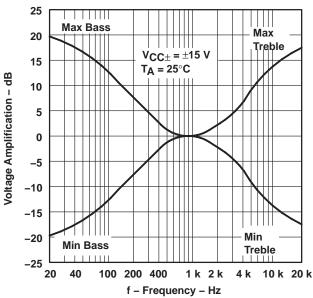


Figure 26. Instrumentation Amplifier



APPLICATION INFORMATION

IC PREAMPLIFIER RESPONSE CHARACTERISTICS



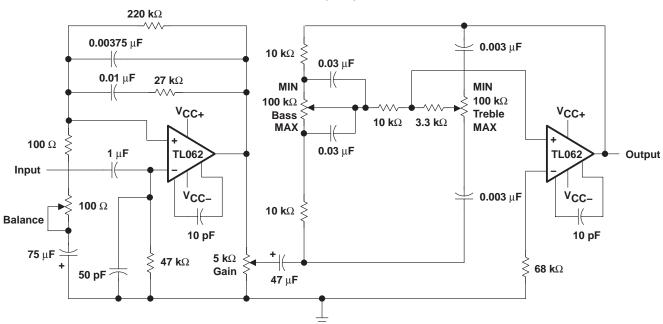


Figure 27. IC Preamplifier



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	n MSL Peak Temp ⁽³⁾
81023012A	OBSOLETE	LCCC	FK	20		None	Call TI	Call TI
81023022A	ACTIVE	LCCC	FK	20	1	None	POST-PLATE	Level-NC-NC-NC
8102302HA	ACTIVE	CFP	U	10	1	None	A42 SNPB	Level-NC-NC-NC
8102302PA	ACTIVE	CDIP	JG	8	1	None	A42 SNPB	Level-NC-NC-NC
81023032A	ACTIVE	LCCC	FK	20	1	None	POST-PLATE	Level-NC-NC-NC
8102303CA	ACTIVE	CDIP	J	14	1	None	A42 SNPB	Level-NC-NC-NC
8102303DA	ACTIVE	CFP	W	14	1	None	A42 SNPB	Level-NC-NC-NC
TL061ACD	ACTIVE	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
TL061ACDR	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
TL061ACP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TL061ACPSR	ACTIVE	SO	PS	8	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
TL061BCD	OBSOLETE	SOIC	D	8		None	Call TI	Call TI
TL061BCP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TL061CD	ACTIVE	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
TL061CDR	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
TL061CP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TL061CPSR	ACTIVE	SO	PS	8	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
TL061CPWLE	OBSOLETE	TSSOP	PW	8		None	Call TI	Call TI
TL061ID	ACTIVE	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
TL061IDR	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
TL061IP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TL061MJG	OBSOLETE	CDIP	JG	8		None	Call TI	Call TI
TL061MJGB	OBSOLETE	CDIP	JG	8		None	Call TI	Call TI
TL062ACD	ACTIVE	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
TL062ACDR	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
TL062ACJG	OBSOLETE	CDIP	JG	8		None	Call TI	Call TI
TL062ACP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TL062ACPSR	ACTIVE	SO	PS	8	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
TL062BCD	ACTIVE	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
TL062BCDR	ACTIVE	SOIC	D	8	2500	Pb-Free	CU NIPDAU	Level-2-250C-1 YEAR





com 18-Feb-2005

TL062CDR	Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TL062CD							(RoHS)		
TL062CDR	TL062BCP	ACTIVE	PDIP	Р	8	50		CU NIPDAU	Level-NC-NC-NC
TL062CJG	TL062CD	ACTIVE	SOIC	D	8	75		CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
TL062CP	TL062CDR	ACTIVE	SOIC	D	8	2500		CU NIPDAU	
TL062CPSLE	TL062CJG	OBSOLETE	CDIP	JG	8		None	Call TI	Call TI
TL062CPSR	TL062CP	ACTIVE	PDIP	Р	8	50		CU NIPDAU	Level-NC-NC-NC
TL062CPW	TL062CPSLE	OBSOLETE	SO	PS	8		None	Call TI	Call TI
TL062CPWLE	TL062CPSR	ACTIVE	SO	PS	8	2000		CU NIPDAU	Level-2-260C-1 YEAR
TL062CPWR	TL062CPW	ACTIVE	TSSOP	PW	8	150		CU NIPDAU	Level-1-250C-UNLIM
TL062ID	TL062CPWLE	OBSOLETE	TSSOP	PW	8		None	Call TI	Call TI
TL062IDR	TL062CPWR	ACTIVE	TSSOP	PW	8	2000		CU NIPDAU	Level-1-250C-UNLIM
TL062IJG	TL062ID	ACTIVE	SOIC	D	8	75		CU NIPDAU	Level-2-250C-1 YEAR
TL062IP	TL062IDR	ACTIVE	SOIC	D	8	2500		CU NIPDAU	Level-2-250C-1 YEAR
TL062IPWR	TL062IJG	OBSOLETE	CDIP	JG	8		None	Call TI	Call TI
TL062MFKB	TL062IP	ACTIVE	PDIP	Р	8	50		CU NIPDAU	Level-NC-NC-NC
TL062MJG ACTIVE CDIP JG 8 1 None A42 SNPB Level-NC-NC-NC-NC TL062MJGB ACTIVE CDIP JG 8 1 None A42 SNPB Level-NC-NC-NC TL064ACD ACTIVE SOIC D 14 50 Pb-Free (RoHS) CU NIPDAU Level-2-250C-1 YEAR TL064ACDR ACTIVE SOIC D 14 2500 Pb-Free (RoHS) CU NIPDAU Level-2-250C-1 YEAR TL064ACN ACTIVE SOIC D 14 50 Pb-Free (RoHS) CU NIPDAU Level-2-250C-1 YEAR TL064BCD ACTIVE SOIC D 14 2500 Pb-Free (RoHS) CU NIPDAU Level-2-250C-1 YEAR TL064BCN ACTIVE SOIC D 14 2500 Pb-Free (RoHS) CU NIPDAU Level-2-260C-1 YEAR TL064CD ACTIVE SOIC D 14 50 Pb-Free (RoHS) CU NIPDAU Level-2-260C-1 YEAR TL064CDR ACTIVE SOIC D	TL062IPWR	ACTIVE	TSSOP	PW	8	2000		CU NIPDAU	Level-1-250C-UNLIM
TL062MJGB ACTIVE CDIP JG 8 1 None A42 SNPB Level-NC-NC-NC TL064ACD ACTIVE SOIC D 14 50 Pb-Free (RoHS) CU NIPDAU Level-2-250C-1 YEAR TL064ACDR ACTIVE SOIC D 14 2500 Pb-Free (RoHS) CU NIPDAU Level-2-250C-1 YEAR TL064ACN ACTIVE PDIP N 14 25 Pb-Free (RoHS) CU NIPDAU Level-2-250C-1 YEAR TL064BCD ACTIVE SOIC D 14 50 Pb-Free (RoHS) CU NIPDAU Level-2-250C-1 YEAR TL064BCN ACTIVE SOIC D 14 2500 Pb-Free (RoHS) CU NIPDAU Level-2-250C-1 YEAR TL064BCN ACTIVE SOIC D 14 25 Pb-Free (RoHS) CU NIPDAU Level-2-260C-1 YEAR TL064CD ACTIVE SOIC D 14 50 Pb-Free (RoHS) CU NIPDAU Level-2-260C-1 YEAR TL064CN ACTIVE SOIC	TL062MFKB	ACTIVE	LCCC	FK	20	1	None	POST-PLATE	Level-NC-NC-NC
TL064ACD ACTIVE SOIC D 14 50 Pb-Free (RoHS) CU NIPDAU Level-2-250C-1 YEAR TL064ACDR ACTIVE SOIC D 14 2500 Pb-Free (RoHS) CU NIPDAU Level-2-250C-1 YEAR TL064ACN ACTIVE PDIP N 14 25 Pb-Free (RoHS) CU NIPDAU Level-NC-NC-NC TL064BCD ACTIVE SOIC D 14 50 Pb-Free (RoHS) CU NIPDAU Level-2-250C-1 YEAR TL064BCDR ACTIVE SOIC D 14 2500 Pb-Free (RoHS) CU NIPDAU Level-2-250C-1 YEAR TL064BCN ACTIVE PDIP N 14 25 Pb-Free (RoHS) CU NIPDAU Level-NC-NC-NC TL064CD ACTIVE SOIC D 14 2500 Pb-Free (RoHS) CU NIPDAU Level-1-235C-UNLIM TL064CDR ACTIVE SOIC D 14 2500 Pb-Free (RoHS) CU NIPDAU Level-1-235C-UNLIM TL064CNSR ACTIVE PDIP <td>TL062MJG</td> <td>ACTIVE</td> <td>CDIP</td> <td>JG</td> <td>8</td> <td>1</td> <td>None</td> <td>A42 SNPB</td> <td>Level-NC-NC-NC</td>	TL062MJG	ACTIVE	CDIP	JG	8	1	None	A42 SNPB	Level-NC-NC-NC
TL064ACDR	TL062MJGB	ACTIVE	CDIP	JG	8	1	None	A42 SNPB	Level-NC-NC-NC
TL064ACN	TL064ACD	ACTIVE	SOIC	D	14	50		CU NIPDAU	Level-2-250C-1 YEAR
TL064BCD	TL064ACDR	ACTIVE	SOIC	D	14	2500		CU NIPDAU	Level-2-250C-1 YEAR
TL064BCDR	TL064ACN	ACTIVE	PDIP	N	14	25		CU NIPDAU	Level-NC-NC-NC
TL064BCN	TL064BCD	ACTIVE	SOIC	D	14	50		CU NIPDAU	Level-2-250C-1 YEAR
TL064CD	TL064BCDR	ACTIVE	SOIC	D	14	2500		CU NIPDAU	Level-2-250C-1 YEAR
TL064CDR	TL064BCN	ACTIVE	PDIP	N	14	25		CU NIPDAU	Level-NC-NC-NC
TL064CN ACTIVE PDIP N 14 25 Pb-Free (RoHS) CU NIPDAU Level-NC-NC-NC (RoHS) TL064CNSR ACTIVE SO NS 14 2000 Pb-Free CU NIPDAU Level-2-260C-1 YEARA	TL064CD	ACTIVE	SOIC	D	14	50		CU NIPDAU	
TL064CN ACTIVE PDIP N 14 25 Pb-Free CU NIPDAU Level-NC-NC-NC (RoHS) TL064CNSR ACTIVE SO NS 14 2000 Pb-Free CU NIPDAU Level-2-260C-1 YEAR	TL064CDR	ACTIVE	SOIC	D	14	2500		CU NIPDAU	
	TL064CN	ACTIVE	PDIP	N	14	25	Pb-Free	CU NIPDAU	Level-NC-NC-NC
	TL064CNSR	ACTIVE	SO	NS	14	2000		CU NIPDAU	



PACKAGE OPTION ADDENDUM

18-Feb-2005

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TL064CPW	ACTIVE	TSSOP	PW	14	90	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
TL064CPWLE	OBSOLETE	TSSOP	PW	14		None	Call TI	Call TI
TL064CPWR	ACTIVE	TSSOP	PW	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
TL064ID	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
TL064IDR	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
TL064IN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TL064MFK	ACTIVE	LCCC	FK	20	1	None	POST-PLATE	Level-NC-NC-NC
TL064MFKB	ACTIVE	LCCC	FK	20	1	None	POST-PLATE	Level-NC-NC-NC
TL064MJ	ACTIVE	CDIP	J	14	1	None	A42 SNPB	Level-NC-NC-NC
TL064MJB	ACTIVE	CDIP	J	14	1	None	A42 SNPB	Level-NC-NC-NC
TL064MWB	ACTIVE	CFP	W	14	1	None	A42 SNPB	Level-NC-NC-NC

 $^{^{(1)}}$ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

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JG (R-GDIP-T8)

CERAMIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP1-T8

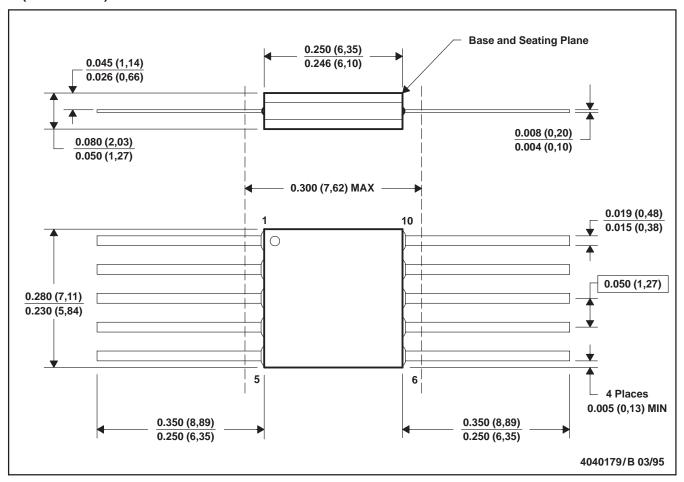
14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

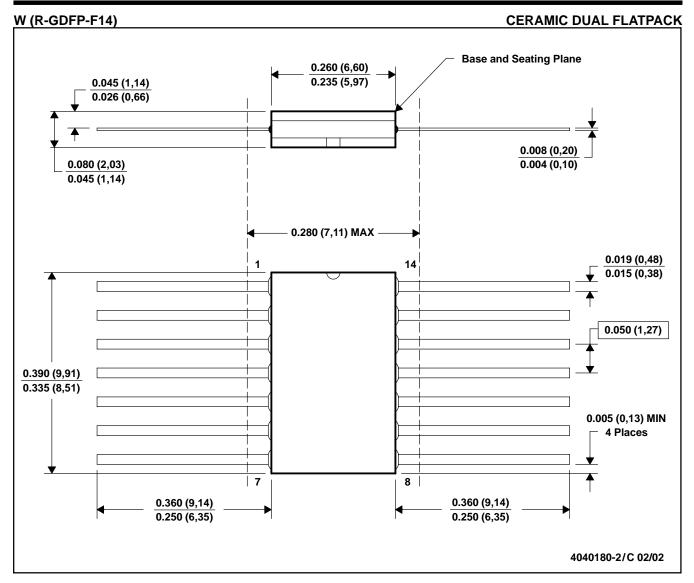
U (S-GDFP-F10)

CERAMIC DUAL FLATPACK



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F10 and JEDEC MO-092AA



- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB

FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001

For the latest package information, go to $http://www.ti.com/sc/docs/package/pkg_info.htm$

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AB.



D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AA.





NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
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